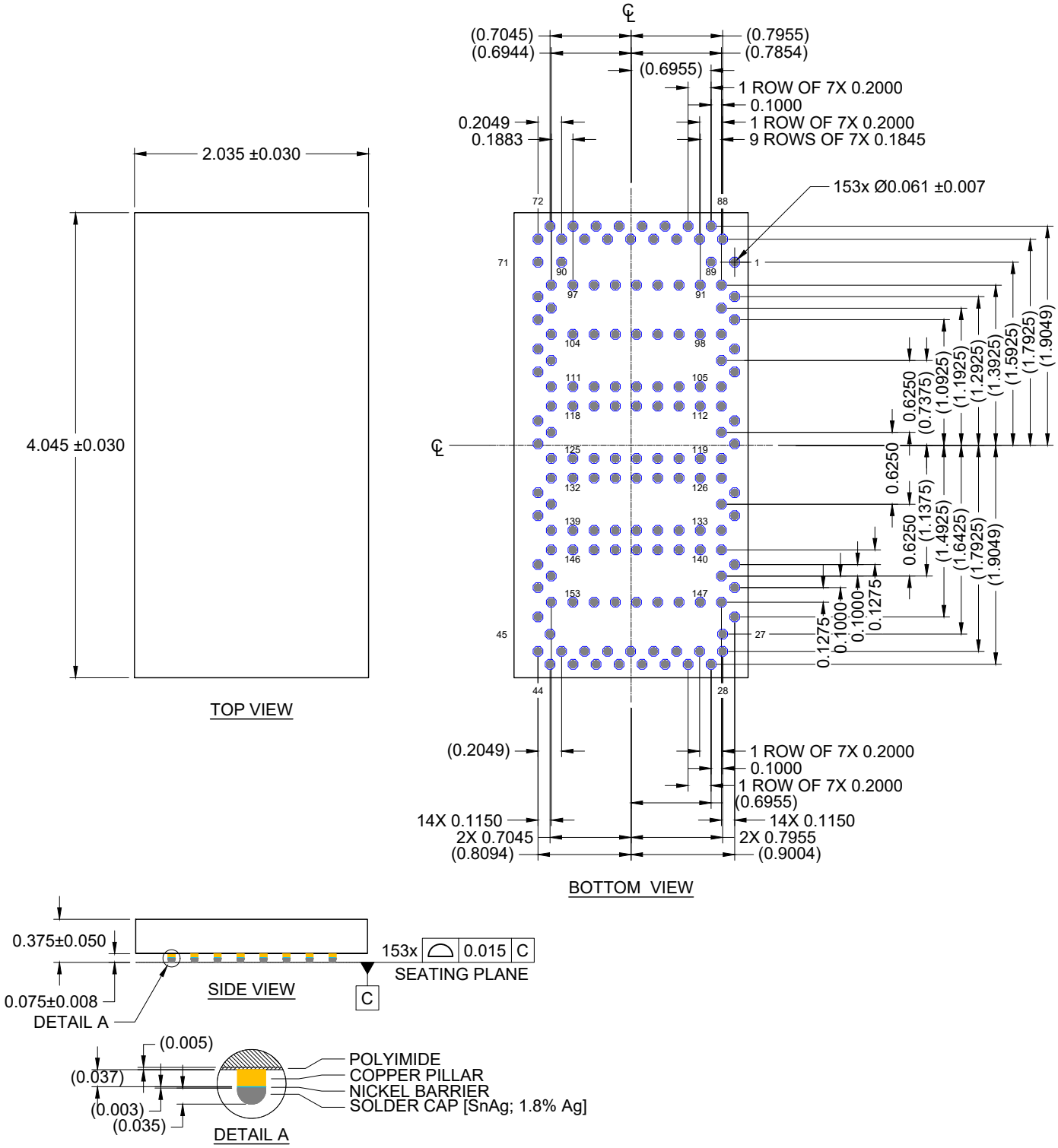
Bumped Die Outline Drawing

PSC-5092-01
XR0153AA
153-Die 2.035 x 4.045 x 0.375 mm Body, 0.150 mm Pitch
Rev.1, Oct 20, 2025



NOTES:

1. All dimensions are in millimeters and angles are in degrees.
2. Use ±0.007 mm for the non-toleranced dimensions.
3. Numbers in ( ) are for references only.

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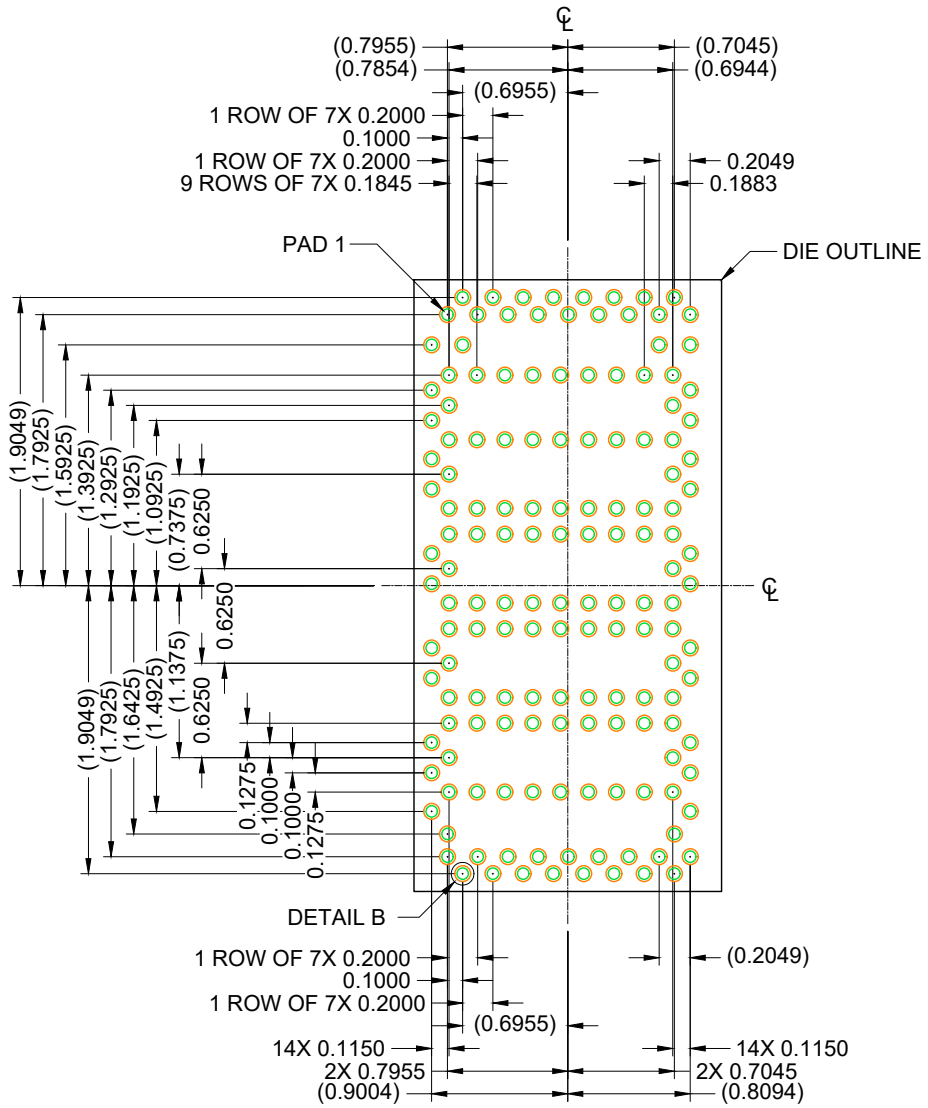
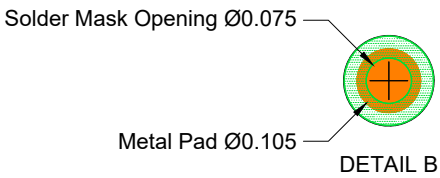


RECOMMENDED LAND PATTERN
(Substrate Top View)



SIDE VIEW CROSS-SECTION OF
BUMP ON PAD FROM DETAIL B

NOTES:

1. All dimensions are in millimeters and angles are in degrees.
2. Land pattern exhibits substrate pads for die bump connections.
3. A complete layout requires additional connections and ground patterns.

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